

WHAT IS CLAIMED IS:

1. A bonding method comprising the steps of:
bringing a first substrate and a second
substrate into contact with each other; and
5 radiating light having a wavelength that
is absorbed into said first substrate but not into said
second substrate, to the interface between said first
substrate and said second substrate for bonding said
first substrate and said second substrate.
- 10 2. A bonding method according to Claim 1 wherein,
at said bonding step, said first substrate and said
second substrate are pressed.
3. A bonding apparatus for bringing a first
substrate and a second substrate into contact with each
15 other for bonding them, comprising:
a light radiating device that radiates
light having a wavelength that is absorbed into said
first substrate but not into said second substrate, to
the interface between said first substrate and said
20 second substrate.
4. A bonding apparatus according to Claim 3,
further comprising a pressure device that is made of a
material which does not absorb the light and that presses
said first substrate and said second substrate.
- 25 5. A bonding apparatus according to Claim 4,
further comprising a sensor that measures a pressure
applied by said pressure device.
6. A bonding apparatus according to Claim 3,
further comprising a temperature adjustment device
30 located near one side of said first substrate opposite to
the side to which light is radiated.
7. A sealing member that is employed as said
second substrate according to the bonding method set
forth in Claim 1 and that is made of quartz, glass, or
35 resin.
8. A sealing member according to Claim 7, wherein
said sealing member has the same shape as said first

substrate and has alignment marks inscribed therein.

9. A sealing member according to Claim 7, wherein said sealing member has recesses that prevent interference with members formed in said first substrate.

5 10. A sealing member according to Claim 7, wherein said sealing member has a light shielding material applied to predetermined part thereof.

10 11. A sealing member that is employed as said second substrate according to the bonding method set forth in Claim 1 and that is realized with a plastic film having thermoplasticity.

12. A sealing member according to Claim 11, wherein said sealing member has alignment marks inscribed therein.

15 13. A sealing member according to Claim 11, wherein said sealing member has a light shielding material applied to predetermined part thereof.

20 14. A sealing member that is employed as said second substrate according to the bonding method set forth in Claim 1 and that has an adhesive which adheres to said first substrate when illuminated with light.

15. A sealing member according to Claim 14, wherein said sealing member has alignment marks inscribed therein.

25 16. A sealing member according to Claim 14, wherein said sealing member has a light shielding material applied to predetermined part thereof.

30 17. A sealing member according to Claim 14, wherein said adhesive itself is heated with radiated light to adhere to said first substrate.

18. A sealing member according to Claim 14, wherein when said first substrate is heated with radiated light, said adhesive is heated to adhere to said first substrate.